

50 AMP PRESS FIT HIGH VOLTAGE DIODES (GPP DIE)

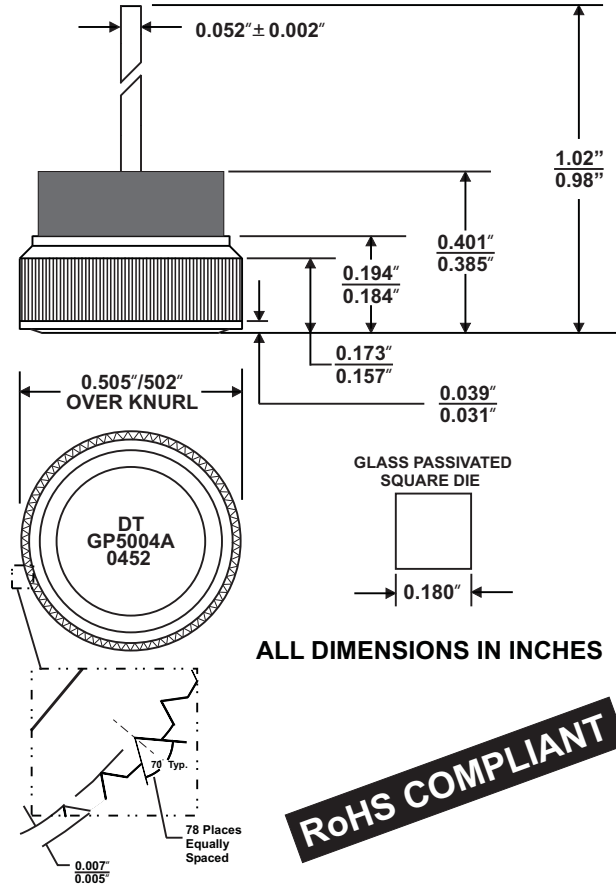
FEATURES

- **VOID FREE VACUUM DIE SOLDERING** For Maximum Mechanical Strength And Heat Dissipation
(Solder Voids: Typical \leq 2%, Max. \leq 5% of Die Area)
- Full Silicon Die Area on P- and N-Sides Are Soldered to Copper Slugs For Minimum Stress And Maximum Heat Dissipation
- Press Fit Into Heat Sink to Further Enhance Heat Handling Capability
- Very Low Resistivity Silicon Die For Lower Operating Junction Temperature
- Very Low Reverse Current Leakage For Minimum Energy Loss

MECHANICAL DATA

- Case: Nickel plated copper
- Finish: All external surfaces are corrosion resistant and the contact areas are readily weldable or solderable
- Maximum Soldering Temperature: 250 °C, 0.25" from case for 10 Seconds
- Mounting Position: Any. Maximum force used for diode insertion to be 12 KN
- Polarity: Color coded epoxy ring- ANODE on LEAD (Beige Ring): Part No.=GP5002PFA/GP5004PFA. CATHODE on LEAD (Black Ring) Part No.=GP5002PFC/GP5004PFC. Part No. marked on cap base.

MECHANICAL SPECIFICATION



ALL DIMENSIONS IN INCHES

RoHS COMPLIANT

MAXIMUM RATINGS & ELECTRICAL CHARACTERISTICS

Ratings at 25 °C ambient temperature unless otherwise specified.

PARAMETER (TEST CONDITIONS)	SYMBOL	RATINGS		UNITS
		GP5002PFA GP5002PFC	GP5004PFA GP5004PFC	
Series Number				
Maximum Recurrent Peak Reverse Voltage	VRRM	200	400	VOLTS
Working Peak Reverse Voltage	VRWM			
Maximum DC Blocking Voltage	VDC			
Non-Repetitive Peak Reverse Voltage (Half Wave, 60 Hz, Single Phase)	VRSM	240	480	
Average Forward Rectified Current	IO	50	50	AMPS
Non-repetitive Peak Forward Surge Current (Half wave, single phase, 60 Hz sine applied to rated load)	IFSM	600	600	
Forward Voltage Drop @ 50Amp DC (Typical) @ 100Amp DC (Typical)	VF	<1.05 <1.20	<1.05 <1.20	VOLTS
Maximum DC Reverse Current at Rated Blocking Voltage Tc = 25 °C	IR	<1.0	<1.0	µA
Junction Operating & Storage Temperature Range	TJ, TSTG	-65 to +200	-65 to +200	°C